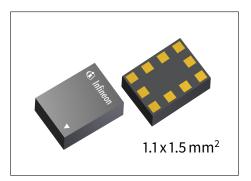




## Low Noise Amplifier with Gain Control

#### Features

- Operating frequencies: 3.4 3.8 GHz
- Insertion power gain: 18.0 dB
- Gain dynamic range: 22 dB
- Low noise figure: 1.3 dB
- Low current consumption: 5.0 mA
- Multi-state control: Gain- and Bypass-Modes
- Small ATSLP leadless package



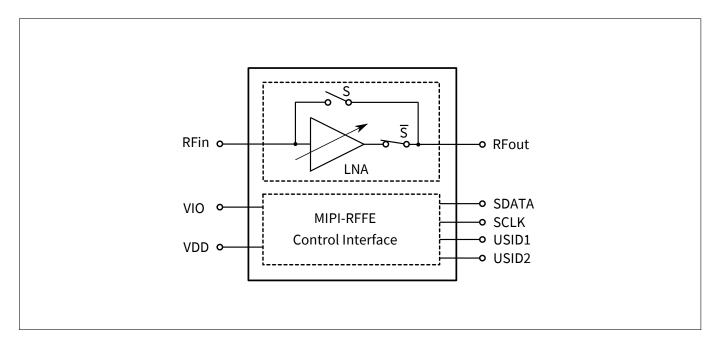
#### Application

The LTE data rate can be significantly improved by using the high gain LNA. The integrated gain control and bypass function increases the overall system dynamic range and leads to more flexibility in the front-end. In high gain mode the BGAV1A10 offers best Noise Figure to ensure high data rates even on the LTE cell edge. Closer to the basestation the bypass mode can be activated reducing current consumption. Thanks to the MIPI control interface, control lines are reduced to a minimum.

#### **Product Validation**

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

#### **Block diagram**



Low Noise Amplifier with Gain Control

Table of Contents

## **Table of Contents**

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**Maximum Ratings** 

### **1 Maximum Ratings**

#### Table 1: Maximum Ratings

Parameter	Symbol		Values		Unit	Note / Test Condition	
		Min.	Тур.	Max.			
Supply Voltage VDD	V <sub>DD</sub>	-0.3	-	2.5	V	1	
Voltage at RFin	V <sub>RFI</sub>	-1	-	1	V	-	
Voltage at RFout	V <sub>RFO</sub>	-1	-	1	V	-	
Current into pin VDD	I <sub>DD</sub>	-30	-	-	mA	-	
RF input power	P <sub>IN</sub>	-	-	25	dBm	-	
Total power dissipation	P <sub>tot</sub>	-	-	90	mW		
Junction temperature	TJ	-	-	150	°C	-	
Ambient temperature range	T <sub>A</sub>	-30	-	85	°C	-	
Storage temperature range	T <sub>STG</sub>	-55	-	150	°C	-	
ESD capability, HBM	V <sub>ESD_HBM</sub>	-1000	-	1000	V	2	
RFFE Supply Voltage	V <sub>IO</sub>	-0.5	-	2.7	V	-	
RFFE Supply Voltage Levels	V <sub>SCLK</sub> ,	-0.7	-	V <sub>IO</sub> +0.7	V	-	
	V <sub>SDATA</sub>			(max. 2.7)			

<sup>1</sup>All voltages refer to GND-Nodes unless otherwise noted

<sup>2</sup>Human Body Model ANSI/ESDA/JEDEC JS-001-2014 ( $R = 1.5 \text{ k}\Omega$ , C = 100 pF).

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit. Exposure to conditions at or below absolute maximum rating but above the specified maximum operation conditions may affect device reliability and life time. Functionality of the device might not be given under these conditions.



**RF Characteristics - Band 42** 

### **2 DC Characteristics**

### Table 3: DC Characteristics at $T_{\rm A}$ = 25 $^{\circ}{\rm C}$

Parameter <sup>1</sup>	Symbol		Values		Unit	Note / Test Condition	
		Min.	Тур.	Max.			
Supply Voltage	V <sub>DD</sub>	1.7	1.8	1.9	V	-	
Supply Current		3.0	5.0	7.0	mA	G0-G3	
Supply Current	I <sub>DD</sub>	-	0.07	0.15	mA	G4	
RFFE supply voltage	V <sub>IO</sub>	1.65	1.8	1.95	V	-	
RFFE input high voltage <sup>2</sup>	V <sub>IH</sub>	0.7 * V <sub>IO</sub>	-	V <sub>IO</sub>	V	-	
RFFE input low voltage <sup>2</sup>	V <sub>IL</sub>	0	-	0.3 * V <sub>IO</sub>	V	-	
RFFE output high voltage <sup>3</sup>	V <sub>OH</sub>	0.8 * V <sub>IO</sub>	-	V <sub>IO</sub>	V	-	
RFFE output low voltage <sup>3</sup>	V <sub>OL</sub>	0	-	0.2 * V <sub>IO</sub>	V	-	
RFFE control input capacitance	C <sub>Ctrl</sub>	-	-	2	рF	-	
RFFE supply current	I <sub>VIO</sub>	-	3	-	μA	Idle State	

<sup>1</sup>Based on the application described in Chapter 6

<sup>2</sup>SCLK and SDATA

<sup>3</sup>SDATA

### 3 RF Characteristics - Band 42

### Table 4: RF Characteristics in ON Mode at $T_A$ = 25 °C, $V_{DD}$ = 1.8 V, $I_{VDD}$ = 5.0 mA, f = 3.4– 3.6 GHz

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Тур.	Max.		
		16.0	18.0	20.0	dB	GO
		13.3	15.3	17.3	dB	G1
Insertion power gain	1/15 12	6.9	8.9	10.9	dB	G2
<i>f</i> = 3500 MHz	$1/ S_{21} ^2$	-2.7	-0.7	1.3	dB	G3
		-4.7	-2.7	-0.7	dB	G3 in Bias0 mode
		-5.4	-3.9	-2.4	dB	G4
		-	1.3	1.8	dB	GO
Noico figuro		-	1.4	1.9	dB	G1
Noise figure f = 3500 MHz	NF	-	1.5	2.0	dB	G2
		-	10.1	11.1	dB	G3
		-	3.9	5.4	dB	G4

Continued on next page



#### **RF Characteristics - Band 42**

#### Table 4: RF Characteristics - Continued from previous page

Parameter	Symbol		Values		Unit	Note / Test Condition
		Min.	Тур.	Max.		
		9	13	-	dB	G0
Input Daturn Laca		9	13	-	dB	G1
Input Return Loss f = 3500 MHz	RL <sub>in</sub>	9	13	-	dB	G2
7 – 3500 MHZ		6	9	-	dB	G3
		3	6	-	dB	G4
		10	20	-	dB	GO
Output Return Loss		10	20	-	dB	G1
f = 3500  MHz	RL <sub>out</sub>	10	25	-	dB	G2
7 – 3300 MHZ		10	18	-	dB	G3
		4	8	-	dB	G4
		26	31	-	dB	G0
Reverse Isolation	$  1/ S_{12} ^2$	29	34	-	dB	G1
f = 3500  MHz		21	26	-	dB	G2
7 – 3300 MHZ		27	32	-	dB	G3
		2.4	3.9	-	dB	G4
Inband input 1dB-compression		-17	-13	-	dBm	GO
point		-17	-13	-	dBm	G1
f = 3500  MHz	IP <sub>1dB</sub>	-10	-6	-	dBm	G2
7 - 5500 MHZ		-1	+3	-	dBm	G3
		-8	-3	-	dBm	G0
Inband input 3 <sup>rd</sup> -order intercept		-8	-3	-	dBm	G1
point <sup>1</sup>	IIP3	-4	+1	-	dBm	G2
point		+4	+9	-	dBm	G3
		27	+32	-	dBm	G4
Phase discontinuity between all		-6	-	6	0	Part to part variation after com-
Gain Mode combinations						pensation in Base Band with
<i>f</i> = 3500 MHz						constant value
Stability	k	> 1	-	-		<i>f</i> = 20 MHz - 10 GHz
	1		1.5	2		50 % last SCLK falling edge to
MIPI to RF time	t <sub>INT</sub>	-	1.5	2	μs	90 % ON, see Fig. 2
Power Up Settling Time	t <sub>BC</sub>	_	10	25	μs	After power down mode

<sup>1</sup>Input power = -30 dBm for each tone for modes G0-G3 / -15 dBm for mode G4,  $f_1$  = 3500 MHz,  $f_2$  =  $f_1$  + 1 MHz

Low Noise Amplifier with Gain Control



**RF Characteristics - Band 43** 

### 4 RF Characteristics - Band 43

### Table 5: RF Characteristics in ON Mode at $T_A$ = 25 °C, $V_{DD}$ = 1.8 V, $I_{VDD}$ = 5.0 mA, f = 3.6– 3.8 GHz

Parameter	Symbol		Values		Unit	Note / Test Condition	
		Min.	Тур.	Max.			
		15.6	17.6	19.6	dB	GO	
		12.8	14.8	16.8	dB	G1	
Insertion power gain	1/10/2	6.4	8.4	10.4	dB	G2	
f = 3700 MHz	$1/ S_{21} ^2$	-2.9	-0.9	1.1	dB	G3	
		-4.9	-2.9	-0.9	dB	G3 in Bias0 mode	
		-5.4	-3.9	-2.4	dB	G4	
		-	1.4	1.9	dB	GO	
Noico figuro		-	1.5	2.0	dB	G1	
Noise figure f = 3700 MHz	NF	-	1.6	2.1	dB	G2	
7 – 3700 MHZ		-	10.2	11.2	dB	G3	
		-	3.9	5.4	dB	G4	
		6	9	-	dB	GO	
Input Return Loss		6	9	-	dB	G1	
f = 3700  MHz	RL <sub>in</sub>	7	10	-	dB	G2	
7 – 3700 MHZ		6	9	-	dB	G3	
		4	7	-	dB	G4	
		10	14	-	dB	G0	
Output Return Loss		10	18	-	dB	G1	
f = 3700  MHz	RL <sub>out</sub>	10	20	-	dB	G2	
7 – 3700 MHZ		10	20	-	dB	G3	
		8	11	-	dB	G4	
		27	32	-	dB	G0	
Reverse Isolation		29	34	-	dB	G1	
f = 3700  MHz	$1/ S_{12} ^2$	22	27	-	dB	G2	
		28	33	-	dB	G3	
		2.4	3.9	-	dB	G4	

Continued on next page



#### **RF Characteristics - Band 43**

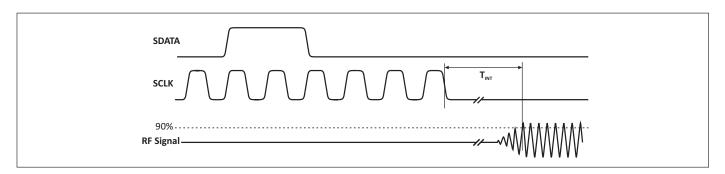
### Table 5: RF Characteristics - Continued from previous page

Parameter	Symbol		Values		Unit	Note / Test Condition	
		Min. Typ.		Max.			
Jude and in put 1dD compression		-18	-14	-	dBm	GO	
Inband input 1dB-compression		-18	-14	-	dBm	G1	
point	IP <sub>1dB</sub>	-9	-5	-	dBm	G2	
f = 3700 MHz		-1	+3	-	dBm	G3	
		-10	-5	-	dBm	GO	
Inhand innut 2rd ander interest		-10	-5	-	dBm	G1	
Inband input 3 <sup>rd</sup> -order intercept	IIP3	-5	0	-	dBm	G2	
point <sup>1</sup>		+2	+7	-	dBm	G3	
		25	+30	-	dBm	G4	
Phase discontinuity between all		-6	_	6	0	Part to part variation after com-	
Gain Mode combinations						pensation in Base Band with	
<i>f</i> = 3700 MHz						constant value	
Stability	k	>1	-	-		<i>f</i> = 20 MHz - 10 GHz	
					μs	50% last SCLK falling edge to	
MIPI to RF time	t <sub>INT</sub>	-	1.5	2		90 % ON, see Fig. 2	
Power Up Settling Time	t <sub>BC</sub>	_	10	25	μs	After power down mode	

<sup>1</sup>Input power = -30 dBm for each tone for modes G0-G3 / -15 dBm for mode G4,  $f_1$  = 3700 MHz,  $f_2$  =  $f_1$  + 1 MHz



**RF Characteristics - Band 43** 



#### Figure 1: MIPI to RF Time

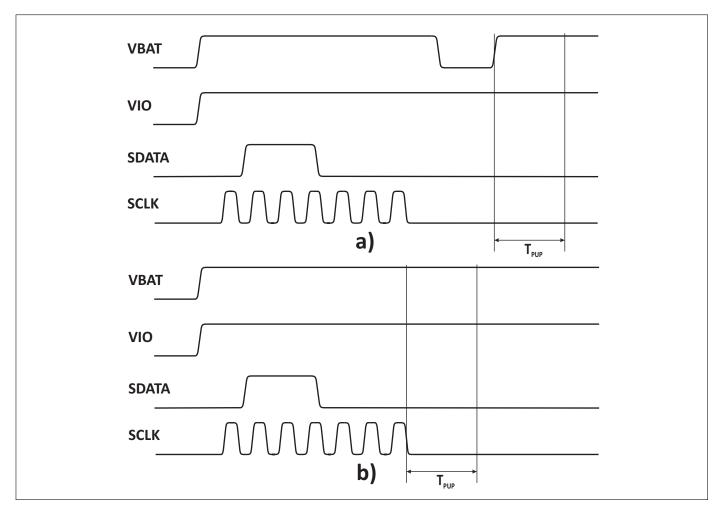


Figure 2: Power-Up Settling Time Definition: a) when the device is already in Active Mode. b) when changing from Low Power Mode to Active Mode.

After Power-Up of VIO the device is set to Low Power Mode. An additional MIPI instruction is necessary to set the device to Active Mode. This case is covered by **b**).



**MIPI RFFE Specification** 

## 5 MIPI RFFE Specification

All sequences are implemented according to the 'MIPI Alliance Specification for RF Front-End Control Interface' document version 2.0 - 25. September 2014.

#### Table 6: MIPI Features

Feature	Supported	Comment
MIPI RFFE 2.0 standard	Yes	
Register 0 write command sequence	Yes	
Register read and write command sequence	Yes	
Extended register read and write command se-	Yes	
quence		
Support for standard frequency range operations	Yes	Up to 26 MHz for read and write
for SCLK		
Support for extended frequency range operations	Yes	Up to 52 MHz for write
for SCLK		
Half speed read	Yes	
Full speed read	Yes	
Full speed write	Yes	
Programmable Group SID	Yes	
Programmable USID	Yes	Support for three registers write and extended write se
		quences
Trigger functionality	Yes	
Broadcast / GSID write to PM TRIG register	Yes	
Reset	Yes	Via VIO, PM TRIG or software register
Status / error sum register	Yes	
Extended product ID register	Yes	
Revision ID register	Yes	
Group SID register	Yes	
USID_Sel pin	Yes	External pin for changing USID:
		USID 12=00 $ ightarrow$ 1000,
		USID 12=10 $ ightarrow$ 1001,
		USID 12=01 $ ightarrow$ 1010,
		USID 12=11 $ ightarrow$ 1011
USID selection via SDATA / SCLK swap feature	No	

#### **Table 7: Startup Behavior**

Feature	State	Comment
Power status	Low power	Lower power mode after start-up
Trigger function Enabled		Enabled after start-up. Programmable via behavior control register



### **MIPI RFFE Specification**

### Table 8: Register Mapping, Table I

Register Address	Register Name	gister Name Data Function Description Bits		Description	Default	Broadcast_ID Support	Trigger Support	R/W
0x00	REGISTER_0	7:0	MODE_CTRL	LNA control	00000000	No	Yes	R/W
0x1C	PM_TRIG	7	PWR_MODE(1), Operation Mode	0: Normal operation (ACTIVE)	1	Yes	No	R/W
				1: Low Power Mode (LOW POWER)	1			
		6	PWR_MODE(0), State Bit Vector	0: No action (ACTIVE)	0			
				1: Powered Reset (STARTUP to ACTIVE				
				to LOW POWER)				
		5	TRIGGER_MASK_2	0: Data masked (held in shadow REG)	0	No		
				1: Data not masked (ready for transfer to active REG)				
		4	TRIGGER_MASK_1	0: Data masked (held in shadow REG)	0			
				1: Data not masked (ready for transfer to active REG)				
		3	TRIGGER_MASK_0	0: Data masked (held in shadow REG)	0			
				1: Data not masked (ready for transfer to active REG)				
		2	TRIGGER_2	0: No action (data held in shadow REG)	0	Yes		
				1: Data transferred to active REG				
		1	TRIGGER_1	0: No action (data held in shadow REG)	0			
				1: Data transferred to active REG				
		0	TRIGGER_0	0: No action (data held in shadow REG)	0			
				1: Data transferred to active REG				
0x1D	PRODUCT_ID	7:0	PRODUCT_ID	This is a read-only register. However, during the programming of the USID a write command sequence is performed on this register, even though the write does not change its value.	00001101	No	No	R
0x1E	MAN_ID	7:0	MANUFACTURER_ID [7:0]	This is a read-only register. However, during the programming of the USID, a write command sequence is performed on this register, even though the write does not change its value.	00011010	No	No	R
0x1F	MAN_USID	7:6	RESERVED	Reserved for future use	00	No	No	R
		5:4	MANUFACTURER_ID [9:8]	These bits are read-only. However, dur- ing the programming of the USID, a write command sequence is performed on this register even though the write does not change its value.	01			
		3:0	USID[3:0]	Programmable USID. Performing a write to this register using the de- scribed programming sequences will program the USID in devices support- ing this feature. These bits store the USID of the device.	See Tab. 6	No	No	R/W



### **MIPI RFFE Specification**

### Table 9: Register Mapping, Table II

Register Address	Register Name	Data Bits	Function	Description	Default	Broadcast_ID Support	Trigger Support	R/W
0x20	EXT_PRODUCT_ID	7:0	EXT_PRODUCT_ID		00000000	No	No	R
0x21	REV_ID	7:4	MAIN_REVISION		0001	No	No	R/W
		3:0	SUB_REVISION		0000			
0x22	GSID	7:4	GSID0[3:0]	Primary Group Slave ID.	0000	No	No	R/W
		3:0	RESERVED	Reserved for secondary Group Slave ID.	0000			
0x23	UDR_RST	7	UDR_RST	Reset all configurable non-RFFE Re- served registers to default values. 0: Normal operation 1: Software reset	0	No	No	R/W
		6:0	RESERVED	Reserved for future use	0000000			
0x24	ERR_SUM	7	RESERVED	Reserved for future use	0	No	No	R
		6	COMMAND_FRAME_PARITY_ERR	Command Sequence received with par- ity error — discard command.	0			
		5	COMMAND_LENGTH_ERR	Command length error.	0			
		4	ADDRESS_FRAME_PARITY_ERR	Address frame with parity error.	0			
		3	DATA_FRAME_PARITY_ERR	Data frame with parity error.	0			
		2	READ_UNUSED_REG	Read command to an invalid address.	0			
		1	WRITE_UNUSED_REG	Write command to an invalid address.	0			
		0	BID_GID_ERR	Read command with a BROADCAST_ID or GROUP_ID.	0			
0x78	DFT	7:0	DESIGN_FOR_TEST	Do not use.	-	-	-	-



### **MIPI RFFE Specification**

#### Table 10: Gain Modes of Operation (Truth Table, Register\_0)

			REGISTER_0 Bits							
State	Mode	D6	D5	D4	D3	D2	D1	DO		
1	Gain G0	1	0	0	1	х	х	х		
2	Gain G1	1	0	1	1	х	х	х		
3	Gain G2	1	1	0	1	х	х	x		
4	Gain G3	1	1	1	0	х	х	х		
5	Gain G4 (Bypass)	0	1	1	1	x	х	х		

#### Table 11: Bias settings (Truth Table, Register\_0)

		REGISTER_0 Bits								
State	Mode	D6	D5	D4	D3	D2	D1	DO		
9	Bias0 (3.0 mA)	1	x	x	x	0	0	0		
10	Bias1 (3.5 mA)	1	x	x	x	0	0	1		
11	Bias2 (4.0 mA)	1	x	x	x	0	1	0		
12	Bias3 (4.5 mA)	1	x	x	x	0	1	1		
13	Bias4 (5.0 mA) <sup>1</sup>	1	x	x	x	1	0	0		
14	Bias5 (5.5 mA)	1	x	x	x	1	0	1		
15	Bias6 (6.0 mA)	1	x	x	x	1	1	0		
16	Bias7 (6.5 mA)	1	x	x	x	1	1	1		

<sup>1</sup>Target bias mode for Gain modes G0-G3

Application Information

**BGAV1A10** 



## **6** Application Information

### **Pin Configuration and Function**

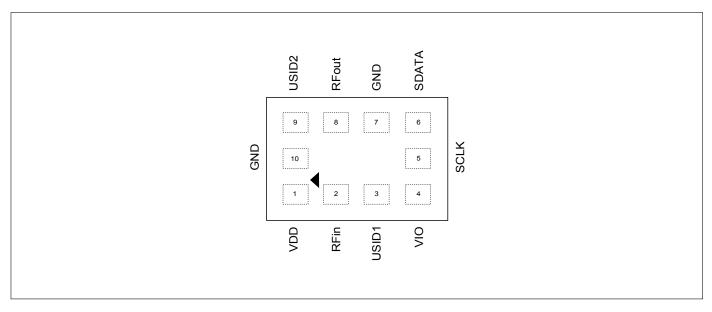


Figure 3: BGAV1A10 Pin Configuration (top view)

#### **Table 12: Pin Definition and Function**

Pin No.	Name	Function
1	VDD	Power supply
2	RFin	RF input port
3	USID1	USID select pin 1
4	VIO	MIPI RFFE supply
5	SCLK	MIPI RFFE clock
6	SDATA	MIPI RFFE data
7	GND	Ground
8	RFout	RF output port
9	USID2	USID select pin 2
10	GND	Ground

<sup>1</sup> Leave unconnected if not used (do NOT connect to GND)

## Low Noise Amplifier with Gain Control



**Application Information** 

### **Application Board Configuration**

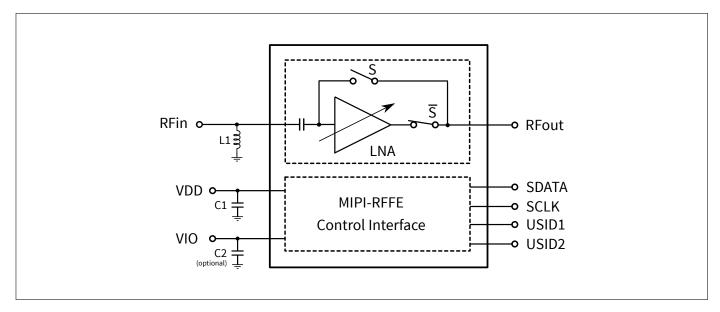


Figure 4: BGAV1A10 Application Schematic

#### **Table 13: Bill of Materials Table**

Name	Value	Package	Manufacturer	Function
C1	10 nF	0201	Various	RF bypass <sup>1</sup>
C2 (optional)	10 nF	0201	Various	RF bypass <sup>1</sup>
L1	1.5nH	0201	muRata LQP type	Input matching <sup>2</sup>
N1	BGAV1A10	ATSLP-10-1	Infineon	Variable gainstep LNA

<sup>1</sup>RF bypass recommended to mitigate power supply noise. <sup>2</sup>The matching elements must be optimized with reference to the frequency band of interest.

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### Low Noise Amplifier with Gain Control



Package Information

## 7 Package Information

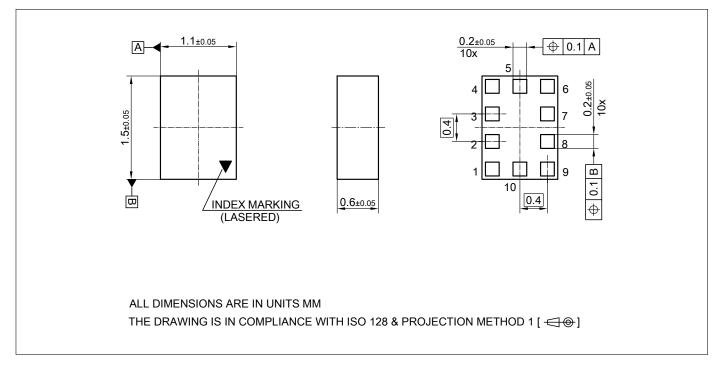


Figure 5: ATSLP-10-1 Package Outline (top, side and bottom views)

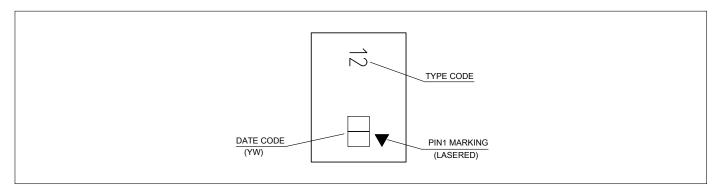


Figure 6: Marking Specification (top view)

Product Name	Marking	Package	
BGAV1A10	V1	ATSLP-10-1	



### Package Information

Table 14: Year date code marking - digit "Y"							
Year	"Y"	Year	"Y"	Year	"Y"		
2000	0	2010	0	2020	0		
2001	1	2011	1	2021	1		
2002	2	2012	2	2022	2		
2003	3	2013	3	2023	3		
2004	4	2014	4	2024	4		
2005	5	2015	5	2025	5		
2006	6	2016	6	2026	6		
2007	7	2017	7	2027	7		
2008	8	2018	8	2028	8		
2009	9	2019	9	2029	9		

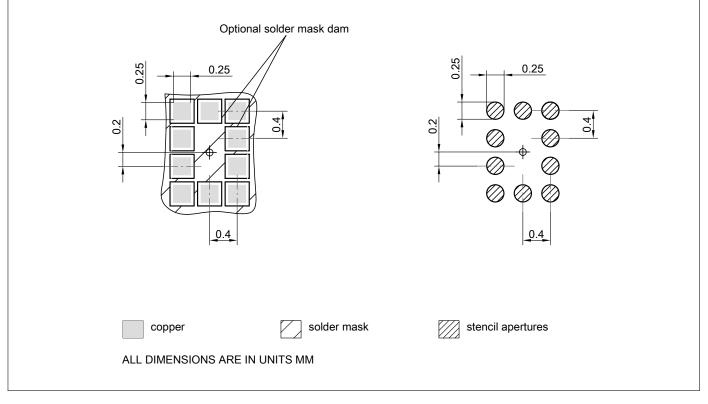
#### Table 14: Year date code marking - digit "Y"

### Table 15: Week date code marking - digit "W"

Week	"W"	Week	"W"	Week	"W"	Week	"W"	Week	"W"
1	А	12	N	23	4	34	h	45	v
2	В	13	Р	24	5	35	j	46	x
3	С	14	Q	25	6	36	k	47	у
4	D	15	R	26	7	37	l	48	z
5	E	16	S	27	а	38	n	49	8
6	F	17	Т	28	b	39	р	50	9
7	G	18	U	29	с	40	q	51	2
8	н	19	V	30	d	41	r	52	3
9	J	20	W	31	e	42	S	53	М
10	к	21	Y	32	f	43	t		
11	L	22	Z	33	g	44	u		



#### **Package Information**



#### Figure 7: Footprint Recommendation

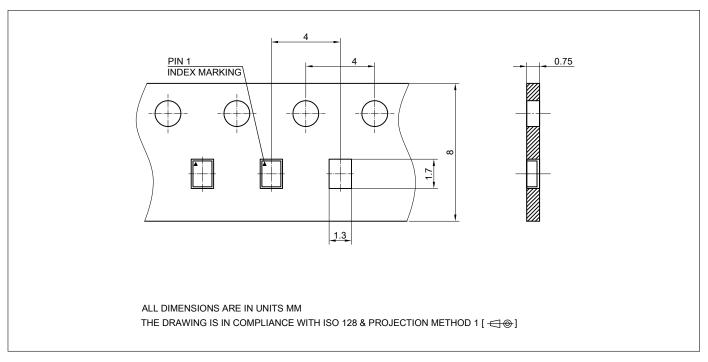


Figure 8: Carrier Tape

Data Sheet

Revision History							
Page or Item	Subjects (major changes since previous revision)						
Revision 3.0, 2018-04-23							
all	"Preliminary" removed						
2	Maximum current into pin VDD updated						
2	Maximum RF input power updated						
2	Maximum total power dissipation updated						
14	Package outline drawing updated						
14	Marking specification drawing updated						
15	Date code marking tables added						
16	Footprint recommendation drawing added						
16	Carrier tape drawing added						
17	Trademarks updated						

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